

### **Amendment to the Claims**

Please cancel claims 37-45 without prejudice to pursuing these claims in a continuation, divisional, continuation-in-part or other application. Please withdraw claims 32-36 and 46. Following is a complete listing of claims, as amended:

1-23. (Cancelled)

24. (Original) A planarizing pad for mechanical and/or chemical-mechanical planarization of a microelectronic-device substrate assembly, comprising:

a planarizing medium having a planarizing surface with a planarizing zone defining a contact area for the substrate assembly;  
at least one optically transmissive window through the planarizing medium, the window being in the planarizing zone; and  
an optical port through the planarizing medium, the port being outside of the planarizing zone.

25. (Original) The pad of claim 24 wherein the optical port comprises a hole through the pad.

26. (Original) The pad of claim 24 wherein the optical port comprises a notch along an edge of the pad.

27. (Previously presented) The pad of claim 24 wherein the at least one window comprises a plurality of windows arranged in a first line for alignment with an opening in a table in a direction generally parallel to a pad travel path, and wherein the pad further comprises a plurality of optical ports arranged in a second line spaced apart from the first line.

28. (Original) The pad of claim 27 wherein the optical ports comprise holes through the pad.

29. (Original) The pad of claim 27 wherein the optical ports comprise notches along an edge of the pad.

30. (Cancelled)

31. (Cancelled)

32. (Withdrawn) A planarizing pad for mechanical and/or chemical-mechanical planarization of a microelectronic-device substrate assembly, comprising:  
a planarizing medium having a planarizing surface with a planarizing zone defining a contact area for the substrate assembly;  
a plurality of optically transmissive windows through the planarizing medium and in the planarizing zone, wherein the plurality of windows are arranged in a first line for alignment with an opening in a table in a direction generally parallel to a pad travel path; and  
a plurality of contour elements arranged in a second line spaced apart from the first line, the contour elements having a surface defining a discrete change in contour on at least one of a backside or an edge of the planarizing medium.

33. (Withdrawn) The pad of claim 32 wherein the contour elements comprise a plurality of indents along the backside of the pad.

34. (Withdrawn) A planarizing pad for mechanical and/or chemical-mechanical planarization of a microelectronic-device substrate assembly, comprising:  
a planarizing medium having a planarizing surface with a planarizing zone defining a contact area for the substrate assembly;  
at least one optically transmissive window through the planarizing medium, the window being in the planarizing zone; and  
a conductive feature on at least one of a backside or along an edge of the planarizing medium.

35. (Withdrawn) The pad of claim 34 wherein the at least one window comprises a plurality of windows arranged in a first line for alignment with an opening in a table in a direction generally parallel to a pad travel path, and wherein the pad further comprises a plurality of conductive features arranged in a second line spaced apart from the first line.

36. (Withdrawn) The pad of claim 35 wherein the conductive features are arranged in a pattern along a backside of the planarizing medium.

37-45. (Cancelled)

46. (Withdrawn) The pad of claim 32 wherein the contour elements comprise a plurality of notches along an edge of the pad.